TENSCON August 4-7, 2025

Wyndham San Diego Bayside || San Diego, CA, USA

Technology Management, Innovation and Leadership for a Sustainable, Flourishing World

HTTPS://TEMSCON-GLOBAL.ORG

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See the conference website for the full **Operating Committee**

DEADLINES

ABSTRACT AND FULL PAPER SUBMISSION

February 15, 2025

WORKSHOP AND SPECIAL SESSION SUBMISSION March 15, 2025

ACCEPTANCE NOTIFICATION April 15, 2025

FINAL MANUSCRIPT SUBMISSION June 1, 2025

Today's world has been profoundly shaped by technological innovation. The scale and impact of technology on tomorrow's world will likely be even greater, with attendant opportunities as well as predicaments. How well we manage technologies and their exploitation will thus substantially determine whether we realize a sustainable and flourishing future for humanity and the planet. From addressing societal challenges to meeting industry needs to facilitating entrepreneurial ventures, addressing imperatives of today and tomorrow will crucially rely on technology management and leadership.

TEMSCON Global is the flagship conference of the IEEE Technology and Engineering Management Society (TEMS) and is a premier venue for research on management, innovation, and leadership across the spectrum of technology, science, and engineering. The conference will convene researchers, managers, practitioners, educators, students, and policy makers to present and discuss new developments in the fields of interest of IEEE TEMS. The conference program will include contributions to this call for papers as well as plenary lectures, invited presentations, innovation and entrepreneurship sessions, and industry forums.

SUBMISSIONS FOR THE TEMSCON GLOBAL PROGRAM

TEMSCON Global welcomes submissions of full papers and extended abstracts. Manuscripts that are accepted and presented will be submitted for inclusion in the IEEE Xplore digital library and indexed by El/Compendex. Authors of selected full papers will be invited to submit extended versions for potential publication in special issues of IEEE Transactions on Engineering Management and IEEE Engineering Management Review. Proposals for workshops and special sessions are also welcome. Refer to the conference website for further details and submission instructions.

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Technology & Engineering Management Society

TOPICS OF INTEREST (PARTIAL LIST)MANAGEMENT OF TECHNOLOGIESGO

- » Machine learning and generative AI
- » Edge and cloud computing
- » Blockchain and distributed ledgers
- » Cybersecurity and quantum
- » Semiconductors and microelectronics

TECHNOLOGY AND BUSINESS STRATEGY

- » Innovation and entrepreneurship
- » R&D and NPD management
- » Supply chain and operations
- » Digital transformation
- » Intellectual property management

IEEE



- » Climate change mitigation and adaptation
- » Sustainability and green tech
- » Smart cities and communities
- » Critical infrastructures and security
- » Smart manufacturing and logistics

SOCIETAL AND INDUSTRY APPLICATIONS

- » Science and technology policy
- » Regulation and compliance
- » Ethics of artificial intelligence
- » National industrial policy
- » Technology transfer

